8-Bit CMOS Microcontroller

C504

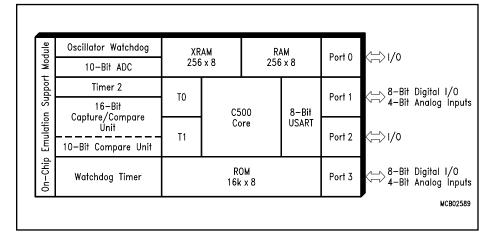
Advance Information

- Fully compatible to standard 8051 microcontroller
- Up to 40 MHz operating frequency
- 16 K×8 ROM (C504-2R only, optional ROM protection)
- 256×8 RAM
- 256×8 XRAM
- Four 8-bit ports, (2 ports with mixed analog/digital I/O capability)
- Three 16-bit timers/counters (timer 2 with up/down counter feature)
- Capture/compare unit for PWM signal generation and signal capturing
 - 3-channel, 16-bit capture/compare unit
 - 1-channel, 10-bit compare unit
- Compare unit
- USART
- 10-bit A/D Converter with 8 multiplexed inputs
- Twelve interrupt sources with two priority levels
- On-chip emulation support logic (Enhanced Hooks Technology TM)
- Programmable 15-bit Watchdog Timer
- Oscillator Watchdog
- · Fast Power On Reset
- Power Saving Modes
- M-QFP-44 package

Temperature ranges: SAB-C504 T_A: 0 to 70°C

SAF-C504 T_A : - 40 to 85°C

SAH-C504 T_A : - 40 to 110°C (max. operating frequency.: TBD) SAK-C504 T_A : - 40 to 125°C (max. operating frequency.: 12 MHz)



The C504 with its capture compare unit (CCU) especially provides a functionality, which allows to use the microcontroller in motor control applications. Further, the C504 is functionally upward compatible with the SAB 80C52/C501 microcontroller and can replace it in existing applications. The C504-2R contains a non-volatile 16K×8 read-only program memory, a volatile on-chip 512×8 read/write data memory, four 8-bit wide ports, three 16-bit timers/counters, a 16-bit capture/compare unit with compare timer, a 10-bit compare timer, a twelve source, two priority level interrupt structure, a serial port, versatile fail save mechanisms, on-chip emulation support logic, and a genuine 10-bit A/D converter. The C504-L is identical to the C504-2R, except that it lacks the program memory on chip. Therefore, the term C504 refers to all versions within this data sheet unless otherwise noted.

Ordering Information

Туре	Ordering Code	Package	Description (8-Bit CMOS microcontroller)
SAB-C504-LM	Q67120-C1048	P-MQFP-44	for external memory (12 MHz)
SAB-C504-L24M	Q67120-C1049	P-MQFP-44	for external memory (24 MHz)
SAB-C504-L40M	Q67120-C1050	P-MQFP-44	for external memory (40 MHz)
SAB-C504-2RM	Q67120-DXXXX	P-MQFP-44	with mask-programmable ROM (12 MHz)
SAB-C504-2R24M	Q67120-DXXXX	P-MQFP-44	with mask-programmable ROM (24 MHz)
SAB-C504-2R40M	Q67120-DXXXX	P-MQFP-44	with mask-programmable ROM (40 MHz)

Note: Versions for extended temperature ranges – 40 °C to 110 °C (SAH-C504) and – 40 °C to 125 °C (SAK-C504) are available on request.

The ordering number of ROM types (DXXXX extensions) is defined after program release (verification) of the customer.

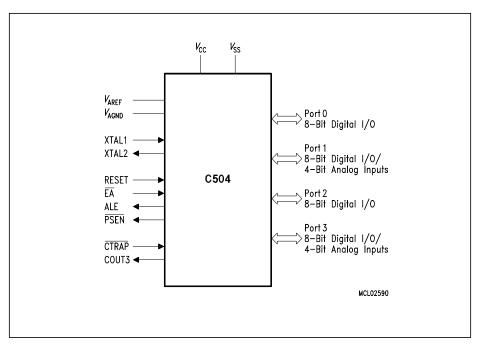


Figure 1 Logic Symbol

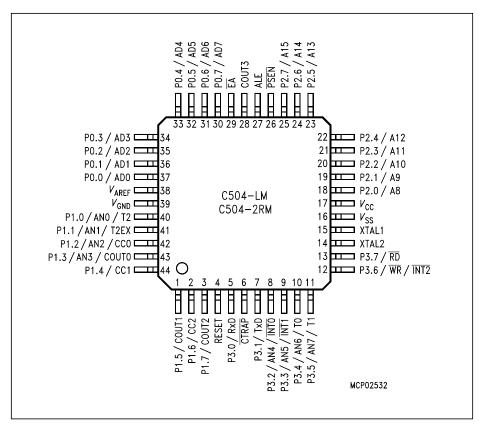


Figure 2
Pin Configuration (Top view)



Table 1
Pin Definitions and Functions

Symbol	Pin Number (P-MQFP-44)	I/O *)	Function						
P1.0-P1.7	40-44,	I/O	Port 1						
	1-3			nal port. Port pins can be used for					
			, , ,	1.0 - P1.3 can also be used as analog					
			1 '	verter. As secondary digital functions, mer 2 pins and the capture/compare					
			port 1 contains the timer 2 pins and the capture/compinputs/outputs. Port 1 pins are assigned to be used						
			analog inputs via the	register P1ANA.					
			The functions are assigned to the pins of port 1 as follows:						
	40		P1.0 / AN0 / T2	Analog input channel 0 /					
	41		P1.1 / AN1 / T2EX	input to counter 2 Analog input channel 1 /					
	41		P1.1/AN1/12EA	capture/reload trigger of timer 2 /					
				up-down count					
	42		P1.2 / AN2 / CC0	Analog input channel 2 /					
				input/output of capture/compare					
	40		DA O / ANIO / OOLITO	channel 0					
	43		P1.3 / AN3 / COUT0	Analog input channel 3 / output of capture/compare					
	44			channel 0					
			P1.4 / CC1	Input/output of capture/compare					
	1			channel 1					
			P1.5 / COUT1	Output of capture/compare					
	2		D4 0 / 000	channel 1					
	3		P1.6 / CC2	Input/output of capture/compare channel 2					
	3		P1.7 / COUT2	Output of capture/compare					
			/ 333.2	channel 2					
RESET	4	ı	RESET						
			,	in for one machine cycle while the					
			oscillator is running resets the device. An internal diffused						
			resistor to V _{SS} permits external capacitor to	s power-on reset using only an					
			external capacitor to	v cc∙					

^{*)} I = Input O = Output



Table 1
Pin Definitions and Functions (cont'd)

Symbol	Pin Number (P-MQFP-44)	I/O *)	Function					
P3.0-P3.7	5, 7-13	I/O	Port 3					
			operate as defined external interrupt additional optinal fi A/D-converter. Po	ional port. P3.0 (R×D) and P3.1 (T×D) for the C501. P3.2 to P3.7 contain the inputs, timer inputs, input and as an unction four of the analog inputs of the ort 3 pins are assigned to be used as				
			P3.6/WR can be a	ne bits of SFR P3ANA. assigned as a third interrupt input. The				
	5		functions are assig P3.0 / RxD	ned to the pins of port 3 as follows: Receiver data input (asynch.) or data input/output (synch.) of serial interface				
	7		P3.1 / TxD	Transmitter data output (asynch.) or clock output (synch.) of serial interface				
	8		P3.2 / AN4 / ĪNT0	Analog input channel 4 / external interrupt 0 input / timer 0 gate control input				
	9		P3.3 / AN5 / ĪNT1	Analog input channel 5 / external interrupt 1 input / timer 1 gate control input				
	10		P3.4 / AN6 / T0	Analog input channel 6 / timer 0 counter input				
	11		P3.5 / AN7 / T1	Analog input channel 7 / timer 1 counter input				
	12		P3.6 / WR / INT2	WR control output; latches the data byte from port 0 into the external data memory /				
	13		P3.7 / RD	external interrupt 2 input RD control output; enables the external data memory				
CTRAP	6	1	unit are switched to register (if they are CTRAP is an input power saving reasons)	the compare outputs of the CAPCOM to the logic level as defined in the COINI e enabled by the bits in SFR TRCON). In with an internal pullup resistor. For ons, the signal source which drives the uld be at high or floating level during.				

^{*)} I = Input O = Output



Table 1
Pin Definitions and Functions (cont'd)

Symbol	Pin Number (P-MQFP-44)	I/O *)	Function
XTAL2	14	-	XTAL2 Output of the inverting oscillator amplifier.
XTAL1	15	-	Input to the inverting oscillator amplifier and input to the internal clock generator circuits. To drive the device from an external clock source, XTAL1 should be driven, while XTAL2 is left unconnected. There are no requirements on the duty cycle of the external clock signal, since the input to the internal clocking circuitry is divided down by a divide-by-two flip-flop. Minimum and maximum high and low times as well as rise/fall times specified in the AC characteristics must be observed.
P2.0-P2.7	18-25	I/O	Port 2 is a bidirectional I/O port with internal pullup resistors. Port 2 pins that have 1s written to them are pulled high by the internal pullup resistors, and in that state can be used as inputs. As inputs, port 2 pins being externally pulled low will source current ($I_{\rm IL}$, in the DC characteris-tics) because of the internal pullup resistors. Port 2 emits the high-order address byte during fetches from external program memory and during accesses to external data memory that use 16-bit addresses (MOVX @DPTR). In this application it uses strong internal pullup resistors when issuing 1s. During accesses to external data memory that use 8-bit addresses (MOVX @Ri), port 2 issues the contents of the P2 special function register.
PSEN	26	0	The Program Store Enable output is a control signal that enables the external program memory to the bus during external fetch operations. It is activated every six oscillator periodes except during external data memory accesses. Remains high during internal program execution.
ALE	27	О	The Address Latch Enable output is used for latching the low-byte of the address into external memory during normal operation. It is activated every six oscillator periodes except during an external data memory access. When instructions are executed from internal ROM (EA=1) the ALE generation can be disabled by bit EALE in SFR SYSCON.

^{*)} I = Input O = Output



Table 1
Pin Definitions and Functions (cont'd)

Symbol	Pin Number (P-MQFP-44)	I/O *)	Function
COUT3	28	0	10-Bit compare channel output This pin is used for the output signal of the 10-bit compare timer 2 unit. COUT3 can be disabled and set to a high or low state.
EA	29	1	External Access Enable When held at high level, instructions are fetched from the internal ROM (C504-2R only) when the PC is less than 4000 _H . When held at low level, the C504 fetches all instructions from external program memory. For the C504-L this pin must be tied low.
P0.0-P0.7	30-37	I/O	Port 0 is an 8-bit open-drain bidirectional I/O port. Port 0 pins that have 1s written to them float, and in that state can be used as high-impendance inputs.Port 0 is also the multiplexed low-order address and data bus during accesses to external program or data memory. In this application it uses strong internal pullup resistors when issuing 1 s. Port 0 also outputs the code bytes during program verification in the C504-2R. External pullup resistors are required during program (ROM) verification.
V_{AREF}	38	-	Reference voltage for the A/D converter.
V_{AGND}	39	-	Reference ground for the A/D converter.
$V_{\mathtt{SS}}$	16	-	Ground (0V)
$V_{\sf CC}$	17	_	Power Supply (+5V)

^{*)} I = Input O = Output



Functional Description

The C504 basic architecture is fully compatible to the standard 8051 microcontroller family. While maintaining all architectural and operational characteristics of the SAB 80C52 / C501, the C504 incorporates some enhancements such as on-chip XRAM, A/D converter, fail save mechanisms, and a versatile capture/compare unit.

Figure 3 shows a block diagram of the C504.

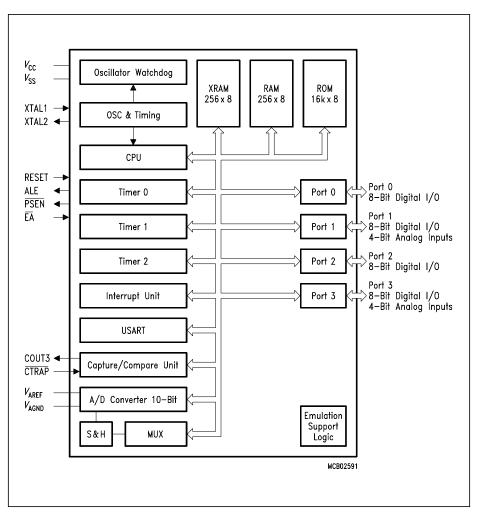


Figure 3
Block Diagram of the C504

Reset Value: 00H

CPU

The C504 is efficient both as a controller and as an arithmetic processor. It has extensive facilities for binary and BCD arithmetic and excels in its bit-handling capabilities. Efficient use of program memory results from an instruction set consisting of 44 % one-byte, 41 % two-byte, and 15 % three-byte instructions. With a 12 MHz crystal, 58 % of the instructions are executed in $1.0\mu s$ (24 MHz: 500 ns, 40 MHz: 300 ns).

Special Function Register PSW (Address D0_H)

Bit No.	MSB							LSB	
	D7 _H	D6 _H	D5 _H	D4 _H	D3 _H	D2 _H	D1 _H	$D0_{H}$	
$D0_{H}$	CY	AC	F0	RS1	RS0	OV	F1	Р	PSW

Bit	Function	Function						
CY	Carry Flag Used by a	g arithmetic i	nstruction.					
AC		Carry Flag	which execute BCD operations.					
F0	General F	Purpose Fla	ag					
RS1 RS0	•		t control bits to select one of the four register banks.					
	RS1	RS0	Function					
	0	0	Bank 0 selected, data address 00 _H -07 _H					
	0	1 Bank 1 selected, data address 08 _H -0F _H						
	1	0	Bank 2 selected, data address 10 _H -17 _H					
	1	1	Bank 3 selected, data address 18 _H -1F _H					
OV	Overflow Used by a	Flag arithmetic i	nstruction.					
F1	General F	Purpose Fla	ag					
P	Set/clear	General Purpose Flag Parity Flag Set/cleared by hardware after each instruction to indicate an odd/even number of "one" bits in the accumulator, i.e. even parity.						



Memory Organization

The C504 CPU manipulates operands in the following four address spaces:

- up to 64 Kbyte of external program memory
- up to 64 Kbyte of external data memory
- 256 bytes of internal data memory
- 256 bytes of internal XRAM data memory
- a 128 byte special function register area

Figure 4 illustrates the memory address spaces of the C504.

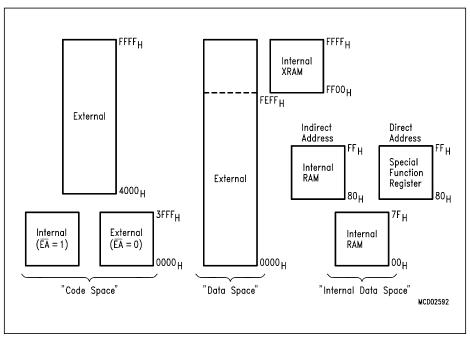


Figure 4 C504 Memory Map

The XRAM in the C504 is a memory area that is logically located at the upper end of the external memory space, but is integrated on the chip. Because the XRAM is used in the same way as external data memory the same instruction types (MOVX instructions) must be used for accessing the XRAM. The XRAM can be enabled and disabled by the XMAP bit in the SYSCON register.

ROM Protection

The C504-2R ROM version allows to protect the content of the internal ROM against read out by non authorized people. The type of ROM protection (protected or unprotected) is fixed with the ROM mask. Therefore, the customer of a C504-2R ROM version has to define whether ROM protection has to be selected or not.

Special Function Registers

All registers, except the program counter and the four general purpose register banks, reside in the special function register area.

The 63 special function register (SFR) include pointers and registers that provide an interface between the CPU and the other on-chip peripherals. There are also 128 directly addressable bits within the SFR area.

The SFRs of the C504 are listed in **table 2** and **table 3**. In **table 2** they are organized in groups which refer to the functional blocks of the C504. **Table 3** illustrates the contents of the SFRs in numeric order of their addresses.



Table 2
Special Function Registers - Functional Blocks

Block	Symbol	Name	Address	Contents after Reset
CPU	ACC B DPH DPL PSW SP SYSCON	Accumulator B-Register Data Pointer, High Byte Data Pointer, Low Byte Program Status Word Register Stack Pointer System Control Register	E0 _H 1) F0 _H 1) 83 _H 82 _H D0 _H 1) 81 _H B1 _H	00H 00H 00H 00H 00H 07H XX10XXX0B ³⁾
Interrupt System	IEN0 IEN1 CCIE ² IP0 IP1 ITCON	Interrupt Enable Register 0 Interrupt Enable Register 1 Capture/Compare Interrupt Enable Reg. Interrupt Priority Register 0 Interrupt Priority Register 1 Interrupt Trigger Condition Register	A8 _H ¹⁾ A9 _H D6 _H B8 _H ¹⁾ B9 _H 9A _H	0X000000B ³⁾ XX000000B ³⁾ 00H XX000000B ³⁾ XX000000B ³⁾ 00101010B
Ports	P0 P1 P1ANA ²⁾ P2 P3 P3ANA ²⁾	Port 0 Port 1 Port 1 Analog Input Selection Register Port 2 Port 3 Port 3 Analog Input Selection Register	80H ¹⁾ 90H ¹⁾ 90H ¹⁾ A0H ¹⁾ B0H ¹⁾	FF _H XXXX1111 _B ³⁾ FF _H FF _H XX1111XX _B ³⁾
A/D- Converter	ADCON0 ADCON1 ADDATH ADDATL P1ANA ²⁾ P3ANA ²⁾	A/D Converter Control Register 0 A/D Converter Control Register 1 A/D Converter Data Register High Byte A/D Converter Data Register Low Byte Port 1 Analog Input Selection Register Port 3 Analog Input Selection Register	D8 _H ¹ DC _H D9 _H DA _H 90 _H ⁴⁾ B0 _H ⁴⁾	XX000000B ³⁾ 01XXX000B ³⁾ 00H 00XXXXXXB ³⁾ XXXX1111B ³⁾ XX1111XXB ³⁾
Serial Channels	PCON 2) SBUF SCON	Power Control Register Serial Channel Buffer Register Serial Channel Control Register	87 _H 99 _H 98 _H 1)	000X0000B XXH ³⁾ 00H
Timer 0/ Timer 1	TCON TH0 TH1 TL0 TL1 TMOD	Timer 0/1 Control Register Timer 0, High Byte Timer 1, High Byte Timer 0, Low Byte Timer 1, Low Byte Timer Mode Register	88 _H ¹⁾ 8C _H 8D _H 8A _H 8B _H 89 _H	00 _H 00 _H 00 _H 00 _H 00 _H

¹⁾ Bit-addressable special function registers

²⁾ This special function register is listed repeatedly since some bits of it also belong to other functional blocks.

³⁾ X means that the value is undefined and the location is reserved

⁴⁾ SFR is located in the mapped SFR area. For accessing this SFR, bit RMAP in SFR SYSCON must be set.



Table 2
Special Function Registers - Functional Blocks (cont'd)

Block	Symbol	Name	Address	Contents after Reset
Timer 2	T2CON T2MOD RC2H RC2L TH2 TL2	Timer 2 Control Register Timer 2 Mode Register Timer 2 Reload Capture Register, High Byte Timer 2 Reload Capture Register, Low Byte Timer 2 High Byte Timer 2 Low Byte	C8 _H ¹⁾ C9 _H CB _H CA _H CD _H CC _H	00 _H XXXXXXXX0 _B ³⁾ 00 _H 00 _H 00 _H
Capture / Compare Unit	CT1CON CCPL CCPH CT1OFL CT1OFH CMSEL0 CMSEL1 COINI TRCON CCL0 CCH0 CCL1 CCH1 CCH2 CCH2 CCIR CCIE ²⁾ CT2CON CP2L CP2H CMP2L CMP2H BCON	Compare timer 1 control register Compare timer 1 period register, low byte Compare timer 1 period register, high byte Compare timer 1 offset register, low byte Compare timer 1 offset register, low byte Compare timer 1 offset register, high byte Capture/compare mode select register 0 Capture/compare mode select register 1 Compare output initialization register Trap enable control register Capture/compare register 0, low byte Capture/compare register 1, low byte Capture/compare register 1, low byte Capture/compare register 2, low byte Capture/compare register 2, low byte Capture/compare register 2, high byte Capture/compare interrupt request flag reg. Capture/compare interrupt enable register Compare timer 2 control register Compare timer 2 period register, low byte Compare timer 2 compare register, high byte Block commutation control register	E1H DEH DFH E6H E7H E3H E2H C7H C2H C3H C5H C6H C7H E5H D6H C1H D2H D3H D4H D5H D7H	00010000B 00H 00H 00H 00H 00H 00H 00H
Watchdog	WDCON WDTREL	Watchdog Timer Control Register Watchdog Timer Reload Register	C0 _H 1) 86 _H	XXXX0000 _B 3)
Power Save Mode	PCON ²⁾ PCON1	Power Control Register Power Control Register 1	87 _H 88 _H 4)	000X0000 _B 3) 0XXXXXXX _B 3)

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Table 3
Contents of the SFRs, SFRs in Numeric Order of their Addresses

Addr	Register	Content after Reset ¹⁾	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
80H ²⁾	P0	FFH	.7	.6	.5	.4	.3	.2	.1	.0
81 _H	SP	07 _H	.7	.6	.5	.4	.3	.2	.1	.0
82 _H	DPL	00 _H	.7	.6	.5	.4	.3	.2	.1	.0
83 _H	DPH	00 _H	.7	.6	.5	.4	.3	.2	.1	.0
86 _H	WDTREL	00H	WDT PSEL	.6	.5	.4	.3	.2	.1	.0
87 _H	PCON	000X- 0000 _B	SMOD	PDS	IDLS	_	GF1	GF0	PDE	IDLE
88H ²⁾	TCON	00 _H	TF1	TR1	TF0	TR0	IE1	IT1	IE0	IT0
88H 3)	PCON1	0XXX- XXXX _B	EWPD	-	-	-	-	-	-	-
89 _H	TMOD	00 _H	GATE	C/T	M1	M0	GATE	C/T	M1	MO
8A _H	TL0	00 _H	.7	.6	.5	.4	.3	.2	.1	.0
8B _H	TL1	00 _H	.7	.6	.5	.4	.3	.2	.1	.0
8C _H	TH0	00 _H	.7	.6	.5	.4	.3	.2	.1	.0
8D _H	TH1	00 _H	.7	.6	.5	.4	.3	.2	.1	.0
90H ²⁾	P1	FFH	.7	.6	.5	.4	.3	.2	T2EX	T2
90H ²⁾³⁾	P1ANA	XXXX- 1111 _B	-	-	-	-	EAN3	EAN2	EAN1	EAN0
98H ²⁾	SCON	00H	SM0	SM1	SM2	REN	TB8	RB8	TI	RI
99H	SBUF	хх _Н	.7	.6	.5	.4	.3	.2	.1	.0
9A _H	ITCON	0010- 1010 _B	IT2	IE2	I2ETF	I2ETR	I1ETF	I1ETR	I0ETF	I0ETR
A0 _{H²⁾}	P2	FFH	.7	.6	.5	.4	.3	.2	.1	.0
A8 _H ²)	IEN0	0X00- 0000 _B	EA	-	ET2	ES	ET1	EX1	ET0	EX0
A9 _H	IEN1	XX00- 0000B	_	_	ECT1	ECCM	ECT2	ECEM	EX2	EADC
B0H ²⁾	P3	FFH	RD	WR	T1	T0	INT1	INT0	TxD	RxD

¹⁾ X means that the value is undefined and the location is reserved

²⁾ Bit-addressable special function registers

³⁾ SFR is located in the mapped SFR area. For accessing this SFR, bit RMAP in SFR SYSCON must be set.

Table 3
Contents of the SFRs, SFRs in Numeric Order of their Addresses (cont'd)

Addr	Register	Content after Reset ¹⁾	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
B0H ²⁾³⁾	P3ANA	XX11- 11XX _B	_	_	EAN7	EAN6	EAN5	EAN4	_	_
B1 _H	SYSCON	XX10- XXX0 _B	_	_	EALE	RMAP	_	_	_	XMAP
B8 _{H²⁾}	IP0	XX00- 0000B	-	-	PT2	PS	PT1	PX1	PT0	PX0
B9 _H	IP1	XX00- 0000B	-	_	PCT1	PCCM	PCT2	PCEM	PX2	PADC
C0 _{H²⁾}	WDCON	XXXX- 0000B	-	-	-	_	OWDS	WDTS	WDT	SWDT
C1 _H	CT2CON	0001- 0000 _B	CT2P	ECT2O	STE2	CT2 RES	CT2R	CLK2	CLK1	CLK0
C2 _H	CCL0	00 _H	.7	.6	.5	.4	.3	.2	.1	.0
СЗН	CCH0	00 _H	.7	.6	.5	.4	.3	.2	.1	.0
C4 _H	CCL1	00 _H	.7	.6	.5	.4	.3	.2	.1	.0
C5 _H	CCH1	00 _H	.7	.6	.5	.4	.3	.2	.1	.0
C6 _H	CCL2	00 _H	.7	.6	.5	.4	.3	.2	.1	.0
C7 _H	CCH2	00 _H	.7	.6	.5	.4	.3	.2	.1	.0
C8 _{H²⁾}	T2CON	00 _H	TF2	EXF2	RCLK	TCLK	EXEN2	TR2	C/T2	CP/ RL2
C9 _H	T2MOD	XXXX- XXX0B	_	_	_	_	_	_	_	DCEN
CAH	RC2L	00 _H	.7	.6	.5	.4	.3	.2	.1	.0
СВН	RC2H	00 _H	.7	.6	.5	.4	.3	.2	.1	.0
CCH	TL2	00 _H	.7	.6	.5	.4	.3	.2	.1	.0
CDH	TH2	00 _H	.7	.6	.5	.4	.3	.2	.1	.0
CFH	TRCON	00 _H	TRPEN	TRF	TREN5	TREN4	TREN3	TREN2	TREN1	TREN0
D0 _{H²⁾}	PSW	00 _H	CY	AC	F0	RS1	RS0	OV	F1	Р
D2 _H	CP2L	00 _H	.7	.6	.5	.4	.3	.2	.1	.0

¹⁾ X means that the value is undefined and the location is reserved

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Table 3
Contents of the SFRs, SFRs in Numeric Order of their Addresses (cont'd)

Addr	Register	Content after Reset ¹⁾	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
D3 _H	CP2H	XXXX. XX00B	-	-	-	-	-	-	.1	.0
D4 _H	CMP2L	00 _H	.7	.6	.5	.4	.3	.2	.1	.0
D5 _H	CMP2H	XXXX. XX00B	_	-	_	_	_	_	.1	.0
D6 _H	CCIE	00H	ECTP	ECTC	CC2 FEN	CC2 REN	CC1 FEN	CC1 REN	CC0 FEN	CC0 REN
D7 _H	BCON	00H	BCMP BCEM	PWM1	PWM0	EBCE	BCERR	BCEN	BCM1	всм0
D8H ²⁾	ADCON0	XX00- 0000 _B	-	-	IADC	BSY	ADM	MX2	MX1	MX0
D9 _H	ADDATH	00H	.9	.8	.7	.6	.5	.4	.3	.2
DA _H	ADDATL	00XX- XXXX _B	.1	.0	-	-	-	-	-	_
DCH	ADCON1	01XX- X000 _B	ADCL1	ADCL0	-	-	-	MX2	MX1	MX0
DEH	CCPL	00H	.7	.6	.5	.4	.3	.2	.1	.0
DFH	ССРН	00H	.7	.6	.5	.4	.3	.2	.1	.0
E0H ²⁾	ACC	00H	.7	.6	.5	.4	.3	.2	.1	.0
E1 _H	CT1CON	0001- 0000 _B	СТМ	ETRP	STE1	CT1 RES	CT1R	CLK2	CLK1	CLK0
E2 _H	COINI	FF _H	COUT 3I	COUTX I	COUT 2l	CC2I	COUT 1I	CC1I	COUT 0I	CC0I
E3 _H	CMSEL0	00 _H	CMSEL 13	CMSEL 12	CMSEL 11	CMSEL 10	CMSEL 03	CMSEL 02	CMSEL 01	CMSEL 00
E4 _H	CMSEL1	00 _H	0	0	0	0	CMSEL 23	CMSEL 22	CMSEL 21	CMSEL 20
E5 _H	CCIR	00 _H	CT1FP	CT1FC	CC2F	CC2R	CC1F	CC1R	CC0F	CC0R
E6 _H	CT10FL	00 _H	.7	.6	.5	.4	.3	.2	.1	.0
E7 _H	CT10FH	00 _H	.7	.6	.5	.4	.3	.2	.1	.0
F0 _{H²⁾}	В	00 _H	.7	.6	.5	.4	.3	.2	.1	.0

¹⁾ X means that the value is undefined and the location is reserved

²⁾ Bit-addressable special function registers



Timer / Counter 0 and 1

Timer/Counter 0 and 1 can be used in four operating modes as listed in table 4.

Table 4
Timer/Counter 0 and 1 Operating Modes

Mode	Description		TMOD				Input Clock		
		Gate	C/T	M1	МО	internal	external (max)		
0	8-bit timer/counter with a divide-by-32 prescaler	Х	Х	0	0	$f_{\rm OSC}/_{12\times32}$	fosc/ _{24×32}		
1	16-bit timer/counter	Х	Х	1	1	$f_{\rm OSC}/_{12}$	$f_{ m OSC}/_{ m 24}$		
2	8-bit timer/counter with 8-bit autoreload	Х	Х	0	0	$f_{\rm OSC}/_{12}$	$f_{ m OSC}/_{24}$		
3	Timer/counter 0 used as one 8-bit timer/counter and one 8-bit timer Timer 1 stops	Х	Х	1	1	fosc/12	fosc/ ₂₄		

In the "timer" function (C/T = '0') the register is incremented every machine cycle. Therefore the count rate is $f_{\rm OSC}/12$.

In the "counter" function the register is incremented in response to a 1-to-0 transition at its corresponding external input pin (P3.4/T0, P3.5/T1). Since it takes two machine cycles to detect a falling edge the max. count rate is $f_{\rm OSC}/24$. External inputs INT0 and INT1 (P3.2, P3.3) can be programmed to function as a gate to facilitate pulse width measurements. **Figure 5** illustrates the input clock logic.

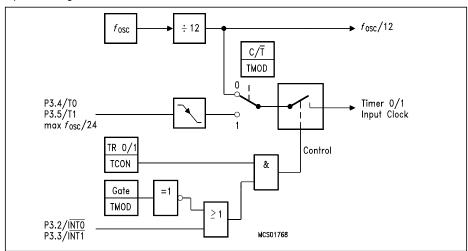


Figure 5
Timer/Counter 0 and 1 Input Clock Logic



Timer 2

Timer 2 is a 16-bit Timer/Counter with an up/down count feature. It can operate either as timer or as an event counter which is selected by bit C/T2 (T2CON.1). It has three operating modes as shown in **table 5**.

Table 5
Timer/Counter 2 Operating Modes

	T:	2CON		T2MOD	T2CON			Input	Clock
Mode	R×CLK or T×CLK	CP/ RL2	TR2	DCEN	EXEN	P1.1/ T2EX	Remarks	internal	external (P1.0/T2)
16-bit Auto-	0	0	1	0	0	Х	reload upon overflow		
reload	0	0	1	0	1	↓ ↓	reload trigger (falling edge)	f _{osc} /12	max $f_{\rm osc}/24$
	0	0	1	1	Х	0	Down counting		
	0	0	1	1	X	1	Up counting		
16-bit Cap- ture	0	1	1	Х	0	Х	16 bit Timer/ Counter (only up-counting)		max
ture	0	1	1	X	1	\	capture TH2, TL2 → RC2H, RC2L	f _{osc} /12	$f_{\rm OSC}/24$
Baud Rate Gene-	1	Х	1	Х	0	Х	no overflow interrupt request (TF2)	<i>c</i> 10	max
rator	1	X	1	X	1	\	extra external interrupt ("Timer 2")	$f_{\rm OSC}/2$	$f_{\rm OSC}/24$
off	Х	Х	0	Х	Х	Х	Timer 2 stops	_	_

Capture/Compare Unit

The Capture / Compare Unit (CCU) of the C504 is built up by a 16-bit 3-channel capture/compare unit (CAPCOM) and a 10-bit 1-channel compare unit (COMP). In compare mode, the CAPCOM unit provides two output signals per channel, which can have inverted signal polarity and non-overlapping pulse transitions. The COMP unit can generate a single PWM output signal and is further used to modulate the CAPCOM output signals. In capture mode, the value of the compare timer 1 is stored in the capture registers if a signal transition occurs at the pins CCx. **Figure 6** shows the block diagram of the CCU.

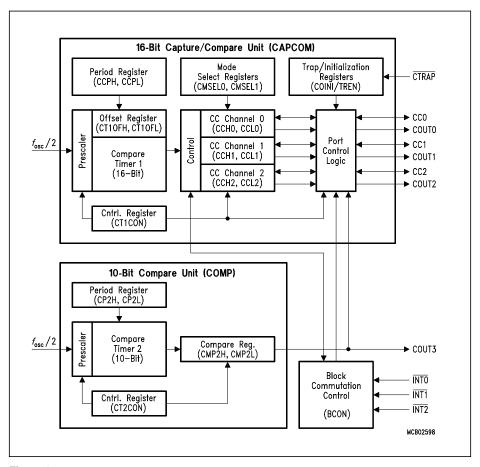


Figure 6
Block Diagram of the CCU

The compare timer 1 and 2 are free running, processor clock coupled 16-bit / 10-bit timers which have each a count rate with a maximum of $f_{\rm OSC}/2$ up to $f_{\rm OSC}/256$. The compare timer operations with its possible compare output signal waveforms are shown in **figure 7**.

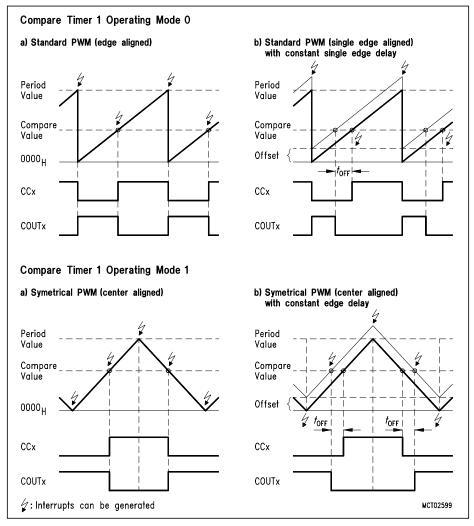


Figure 7
Basic Operating Modes of the CAPCOM Unit

Compare timer 1 runs only in operating mode 1 with one output signal of selectable signal polarity at the pin COUT3.



Serial Interface (USART)

The serial port is full duplex and can operate in four modes (one synchronous mode, three asynchronous modes) as illustrated in **table 6**. The possible baudrates can be calculated using the formulas given in **table 6**.

Table 6
USART Operating Modes

Mada	sc	ON	Baudrate	Description
Mode	SM0	SM1		
0	0	0	f _{osc} /12	Serial data enters and exits through R×D. T×D outputs the shift clock. 8-bit are transmitted/received (LSB first)
1	0	1	Timer 1/2 overflow rate	8-bit UART 10 bits are transmitted (through T×D) or received (R×D)
2	1	0	$f_{ m osc}$ /32 or $f_{ m osc}$ /64	9-bit UART 11 bits are transmitted (T×D) or received (R×D)
3	1	1	Timer 1/2 overflow rate	9-bit UART Like mode 2 except the variable baud rate

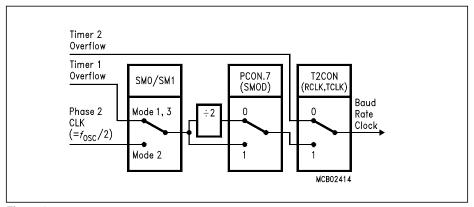


Figure 8
Block Diagram of Baud Rate Generation for the Serial Interface



The possible baudrates can be calculated using the formulas given in table 7.

Table 7 Formulas for Calculating Baudrates

Baud Rate derived from	Interface Mode	Baudrate
Oscillator	0 2	$f_{\rm OSC}/12$ (2 ^{SMOD} × $f_{\rm OSC}$) / 64
Timer 1 (16-bit timer) (8-bit timer with 8-bit autoreload)	1,3 1,3	(2 ^{SMOD} \times timer 1 overflow rate) /32 (2 ^{SMOD} \times $f_{\rm OSC}$) / (32 \times 12 \times (256-TH1))
Timer 2	1,3	$f_{\rm OSC}$ / (32 × (65536-(RC2H, RC2L))



10-Bit A/D Converter

The C504 has a high performance 10-bit A/D converter (**figure 9**) with 8 inputs included which uses successive approximation technique for the conversion of analog input voltages.

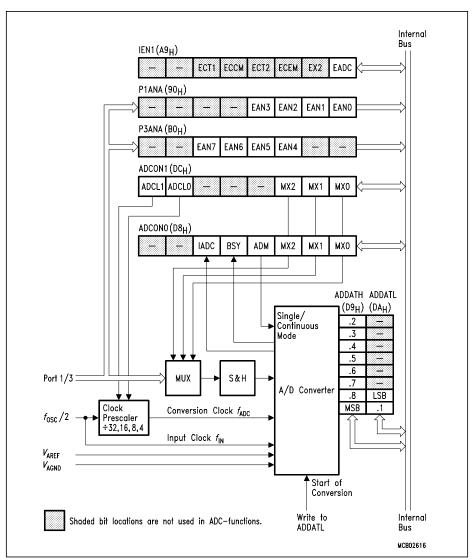


Figure 9
A/D Converter Block Diagram

The A/D converter uses two clock signals for operation : the conversion clock f_{ADC} (= 1/ t_{ADC}) and the input clock f_{IN} (= 1/ t_{IN}). Both clock signals are derived from the C504 system clock f_{OSC} which is applied at the XTAL pins. The duration of an A/D conversion is a multiple of the period of the f_{IN} clock signal. The table in **figure 10** shows the prescaler ratios and the resulting A/D conversion times which must be selected for typical system clock rates.

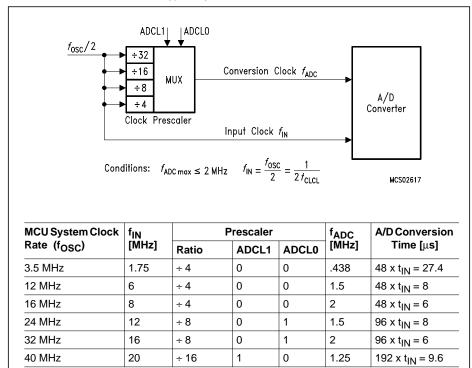


Figure 10
A/D Converter Clock Selection

The analog inputs are located at port 1 and port 3 (4 lines on each port). The corresponding port 1 and port 3 pins have a port structure, which allows to use it either as digital I/Os or analog inputs. The analog input function of these mixed digital/analog port lines is selected via the registers P1ANA and P3ANA.



Interrupt System

The C504 provides 12 interrupt sources with two priority levels. **Figure 11** and **12** give a general overview of the interrupt sources and illustrate the interrupt request and control flags.

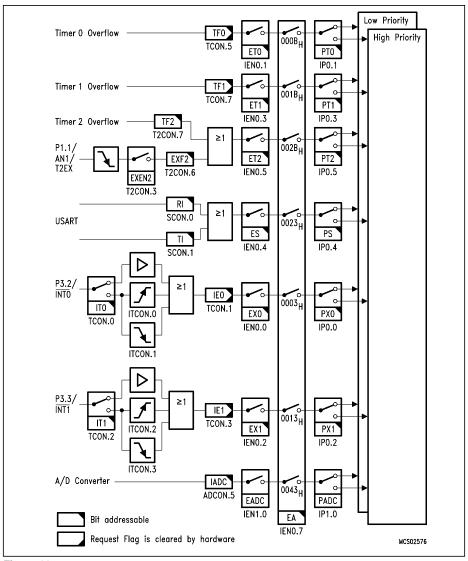


Figure 11
Interrupt Request Sources (Part 1)

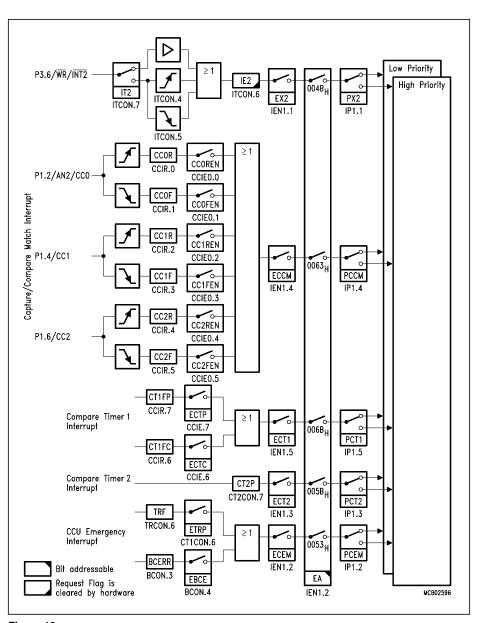


Figure 12 Interrupt Request Sources (Part 2)



Table 8 Interrupt Vector Addresses

Request Flags	Interrupt Source	Vector Address
IE0	External interrupt 0	0003 _H
TF0	Timer 0 interrupt	000B _H
IE1	External interrupt 1	0013 _H
TF1	Timer 1 interrupt	001B _H
RI + TI	Serial port interrupt	0023 _H
TF2 + EXF2	Timer 2 interrupt	002B _H
IADC	A/D converter interrupt	0043 _H
IE2	External interrupt 2	004B _H
TRF, BCERR	CAPCOM emergency interrupt	0053 _H
CT2P	Compare timer 2 interrupt	005B _H
CC0F-CC2F, CC0R-CC2R	Capture / compare match interrupt	0063 _H
CT1FP, CT1FC	Compare timer 1 interrupt	006B _H
	Power-down interrupt	007B _H

A low-priority interrupt can itself be interrupted by a high-priority interrupt, but not by another low-priority interrupt. A high-priority interrupt cannot be interrupted by any other interrupt source. If two requests of different priority level are received simultaneously, the request of higher priority is serviced. If requests of the same priority are received simultaneously, an internal polling sequence determines which request is serviced. Thus within each priority level there is a second priority structure determined by the polling sequence as shown in **table 9**.

Table 9
Interrupt Source Structure

Interrupt Source		Priority
High Priority	— Low Priority	
External Interrupt 0	A/D Converter	High h
Timer 0 Interrupt	External Interrupt 2	
External Interrupt 1	CCU Emergency Interrupt	
Timer 1 Interrupt	Compare Timer 2 Interrupt	<u> </u>
Serial Channel	Capture / Compare Match Interrupt	Y
Timer 2 Interrupt	Compare Timer 1 Interrupt	Low

Fail Save Mechanisms

The C504 offers enhanced fail safe mechanisms, which allow an automatic recovery from software upset or hardware failure.

- 15-bit reloadable watchdog timer
- Oscillator Watchdog

Watchdog Timer

The watchdog timer in the C504 is a 15-bit timer, which is incremented by a count rate of either f_{SOO} 12 or $f_{\text{CYCLE}}/32$. From the 15-bit watchdog timer count value only the upper 7 bits can be programmed. **Figure 5** shows the block diagram of the programmable watchdog timer.

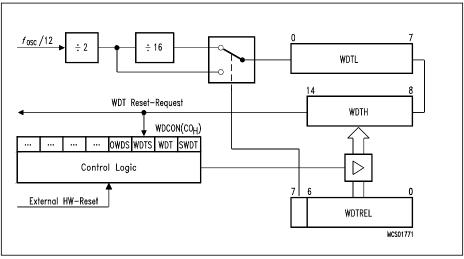


Figure 13
Block Diagram of the Programmable Watchdog Timer

The watchdog timer can be started by software (bit SWDT in SFR WDCON), but it cannot be stopped during active mode of the device. If the software fails to refresh the running watchdog timer an internal reset will be initiated. The reset cause (external reset or reset caused by the watchdog) can be examined by software (status flag WDTS in WDCON is set). A refresh of the watchdog timer is done by setting bits WDT (SFR WDCON) and SWDT consecutively. This double instruction sequence has been implemented to increase system security.

It must be noted, however, that the watchdog timer is halted during the idle mode and power down mode of the processor. Therefore, it is possible to use the idle mode in combination with the watchdog timer function.



Oscillator Watchdog

The oscillator watchdog of the C504 serves for three functions:

- Monitoring of the on-chip oscillator's function

The watchdog supervises the on-chip oscillator's frequency; if it is lower than the frequency of an auxiliary RC oscillator, the internal clock is supplied by this RC oscillator and the C504 is put into reset state; if the failure condition again disappears, the part executes a final reset phase of typ. 1 ms in order to allow the oscillator to stabilize; then the oscillator watchdog reset is released and the part starts program execution again.

- Fast internal reset after power-on

The oscillator watchdog unit provides a clock supply for the reset before the on-chip oscillator has started. The oscillator watchdog unit also works identically to the monitoring function.

- Control of external wake-up from software power-down mode

When the power-down mode is left by a low level at the $\overline{\text{INTO}}$ pin, the oscillator watchdog unit assures that the microcontroller resumes operation (execution of the power-down wake-up interrupt) with the nominal clock rate. In the power-down mode the RC oscillator and the on-chip oscillator are stopped. Both oscillators are started again when power-down mode is released. When the on-chip oscillator has a higher frequency than the RC oscillator, the microcontroller starts operation after a final delay of typ. 1 ms in order to allow the on-chip oscillator to stabilize.

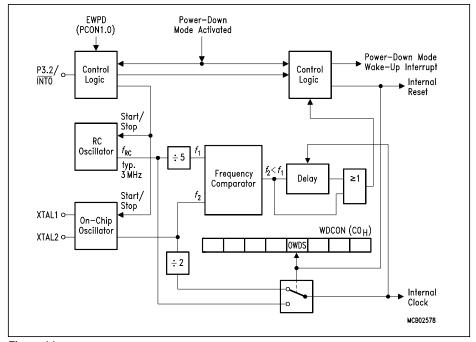


Figure 14 Block Diagram of the Programmable Watchdog Timer



Power Saving Modes

Two power down modes are available, the idle mode and power down mode.

- In the <u>idle mode</u> the oscillator of the C504 continues to run, but the CPU is gated off from the clock signal. However, the interrupt system, the serial port, the A/D converter, and all timers with the exception of the watchdog timer are further provided with the clock. The CPU status is preserved in its entirety: the stack pointer, program counter, program status word, accumulator, and all other registers maintain their data during idle mode.
- In the <u>power down</u> mode, the RC oscillator and the on-chip oscillator which operates with the XTAL pins is stopped. Therefore all functions of the microcontroller are stopped and only the contents of the on-chip RAM, XRAM and the SFR's are maintained. The port pins, which are controlled by their port latches, output the values that are held by their SFR's.

Table 10 gives a general overview of the power saving modes.

Table 10
Power Saving Modes Overview

Mode	Entering 2-Instruction Example	Leaving by	Remarks	
Idle mode	ORL PCON, #01H ORL PCON, #20H	Ocurrence of an interrupt from a peripheral unit	CPU clock is stopped; CPU maintains their data; peripheral units are active (if	
		Hardware Reset	enabled) and provided with clock	
Power-Down	ORL PCON, #02H	Hardware Reset	Oscillator is stopped;	
Mode	ORL PCON, #40H	Wake-up from power down	contents of on-chip RAM and SFR's are maintained;	

In the power down mode of operation, $V_{\rm CC}$ can be reduced to minimize power consumption. It must be ensured, however, that $V_{\rm CC}$ is not reduced before the power down mode is invoked, and that $V_{\rm CC}$ is restored to its normal operating level, before the power down mode is terminated.

The idle mode can be terminated by activating any enabled peripheral interrupt or by resetting the C504. The power down mode can be terminated using an interrupt by a short low pulse at the pin P3.2/AN4/INTO or by resetting the C504. If a power saving mode is left through an interrupt, the microcontroller state (CPU, ports, peripherals) remains preserved. If a power saving mode is left by a reset operation, the microcontroller state is disturbed and replaced by the reset state of the C504.

Absolute Maximum Ratings

Ambient temperature under bias (T_A)	0 °C to + 70 °C
Storage temperature (T_{ST})	65 °C to + 150 °C
Voltage on $V_{\rm CC}$ pins with respect to ground ($V_{\rm SS}$)	– 0.5 V to 6.5 V
Voltage on any pin with respect to ground (V_{SS})	– 0.5 V to $V_{\rm CC}$ + 0.5 V
Input current on any pin during overload condition	10 mA to + 10 mA
Absolute sum of all input currents during overload condition	100 mA
Power dissipation	TBD

Note:

Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage of the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for longer periods may affect device reliability. During overload conditions ($V_{\rm IN} > V_{\rm CC}$ or $V_{\rm IN} < V_{\rm SS}$) the Voltage on $V_{\rm CC}$ pins with respect to ground ($V_{\rm SS}$) must not exceed the values defined by the absolute maximum ratings.

DC Characteristics

$V_{\rm CC}$ = 5 V + 10%, - 15%; $V_{\rm SS}$ = 0 V	$T_{\rm A}$ = 0 to 70 °C	for the SAB-C504
	$T_{\rm A}$ = $-$ 40 to 85 $^{\circ}$ C	for the SAF-C504
	$T_{\rm A}$ = $-$ 40 to 110 °C	for the SAH-C504
	$T_{\wedge} = -40 \text{ to } 125 ^{\circ}\text{C}$	for the SAK-C504

Parameter	Symbol	Limit	Values	Unit	Test Condition	
		min.	max.	1		
Input low voltage (except \overline{EA} , RESET, \overline{CTRAP})	V_{IL}	- 0.5	0.2 V _{CC} - 0.1	V	_	
Input low voltage (EA)	V_{IL1}	- 0.5	0.2 V _{CC} - 0.3	V	_	
Input low voltage (RESET, CTRAP)	V_{IL2}	- 0.5	0.2 V _{CC} + 0.1	V	_	
Input high voltage (except XTAL1, RESET and CTRAP)	V_{IH}	0.2 V _{CC} + 0.9	V _{CC} + 0.5	V	_	
Input high voltage to XTAL1	V_{IH1}	0.7 V _{CC}	$V_{\rm CC}$ + 0.5	V	_	
Input high voltage to RESET and CTRAP	V_{IH2}	0.6 V _{CC}	V _{CC} + 0.5	V	_	
Output low voltage (ports 1, 2, 3, COUT3)	V_{OL}	_	0.45	V	$I_{\rm OL}$ = 1.6 mA ¹⁾	
Output low voltage (port 0, ALE, PSEN)	V_{OL1}	_	0.45	V	$I_{\rm OL}$ = 3.2 mA ¹⁾	
Output high voltage (ports 1, 2, 3)	V_{OH}	2.4 0.9 V _{CC}		V	$I_{\text{OH}} = -80 \mu\text{A},$ $I_{\text{OH}} = -10 \mu\text{A}$	
Output high voltage (ports 1,3 pins in push-pull mode and COUT3)	V_{OH1}	0.9 V _{CC}	_	V	$I_{\rm OH} = -800~\mu{\rm A}$	
Output high voltage (port 0 in external bus mode, ALE, PSEN)	V_{OH2}	2.4 0.9 V _{CC}	_	V	$I_{OH} = -800 \mu A^{2}$, $I_{OH} = -80 \mu A^{2}$	
Logic 0 input current (ports 1, 2, 3)	I_{IL}	- 10	- 50	μΑ	$V_{\rm IN} = 0.45 \ { m V}$	
Logical 1-to-0 transition current (ports 1, 2, 3)	I_{TL}	- 65	- 650	μА	<i>V</i> _{IN} = 2 V	
Input leakage current (port 0, EA)	I_{LI}	_	± 1	μΑ	$0.45 < V_{\rm IN} < V_{\rm CC}$	
Pin capacitance	C_{IO}	_	10	pF	$f_{\rm c}$ = 1 MHz, $T_{\rm A}$ = 25 °C	
Overload current	I_{OV}	-	±5	mA	7) 8)	

Parameter	Symbol	Limit Values		Unit	Test Condition	
		typ. 9)	max.			
Power supply current:						
Active mode, 12 MHz 4)	$I_{\rm CC}$	16	TBD	mA	$V_{\rm CC}$ = 5 V, 4)	
Idle mode, 12 MHz 5)	$I_{\rm CC}$	8	TBD	mA	$V_{\rm CC} = 5 \text{ V}, 5)$	
Active mode, 24 MHz 4)	$I_{\rm CC}$	25	TBD	mA	$V_{\rm CC}$ = 5 V, 4)	
Idle mode, 24 MHz 5)	$I_{\rm CC}$	13	TBD	mA	$V_{\rm CC} = 5 \text{ V}, 5)$	
Active mode, 40 MHz 4)	$I_{\rm CC}$	38	TBD	mA	$V_{\rm CC}$ = 5 V, 4)	
Idle mode, 40 MHz 5)	$I_{\rm CC}$	17	TBD	mA	$V_{\rm CC} = 5 \text{ V}, ^{5)}$	
Power-down mode	I_{PD}	1	50	μΑ	$V_{\rm CC} = 25.5 V^{(3)}$	

- 1) Capacitive loading on ports 0 and 2 may cause spurious noise pulses to be superimposed on the V_{OL} of ALE and port 3. The noise is due to external bus capacitance discharging into the port 0 and port 2 pins when these pins make 1-to-0 transitions during bus operation. In the worst case (capacitive loading > 100 pF), the noise pulse on ALE line may exceed 0.8 V. In such cases it may be desirable to qualify ALE with a schmitt-trigger, or use an address latch with a schmitt-trigger strobe input.
- Capacitive loading on ports 0 and 2 may cause the V_{OH} on ALE and PSEN to momentarily fall below the 0.9 V_{CC} specification when the address lines are stabilizing.
- 3) I_{PD} (power-down mode) is measured under following conditions:
 EA = Port0 = V_{CC}; RESET = V_{SS}; XTAL2 = N.C.; XTAL1 = V_{SS}; V_{AGND} = V_{SS}; all other pins are disconnected.
- 4) $I_{\rm CC}$ (active mode) is measured with: XTAL1 driven with $t_{\rm CLCH}$, $t_{\rm CHCL}$ = 5 ns , $V_{\rm IL}$ = $V_{\rm SS}$ + 0.5 V, $V_{\rm IH}$ = $V_{\rm CC}$ 0.5 V; XTAL2 = N.C.; EA = Port0 = Port1 = RESET = $V_{\rm CC}$; all other pins are disconnected. $I_{\rm CC}$ would be slightly higher if a crystal oscillator is used (appr. 1 mA).
- 5) I_{CC} (idle mode) is measured with all output pins disconnected and with all peripherals disabled; XTAL1 driven with t_{CLCH}, t_{CHCL} = 5 ns, V_{IL} = V_{SS} + 0.5 V, V_{IH} = V_{CC} - 0.5 V; XTAL2 = N.C.; RESET = EA = V_{SS}; Port0 = V_{CC}; all other pins are disconnected.
- 6) I_{CC max} at other frequencies is given by: active mode: TBD

active mode: TBD idle mode: TBD

where $f_{\rm OSC}$ is the oscillator frequency in MHz. $I_{\rm CC}$ values are given in mA and measured at $V_{\rm CC}$ = 5 V.

- 7) Overload conditions occur if the standard operating conditions are exceeded, i.e. the voltage on any pin exceeds the specified range (i.e. $V_{\rm OV} > V_{\rm CC} + 0.5$ V or $V_{\rm OV} < V_{\rm SS} 0.5$ V). The supply voltage $V_{\rm CC}$ and $V_{\rm SS}$ must remain within the specified limits. The absolute sum of input currents on all port pins may not exceed 50 mA
- 8) Not 100 % tested, guaranteed by design characterization.
- 9) The typical $I_{\rm CC}$ values are periodically measured at $T_{\rm A}$ = +25 °C but not 100% tested.



A/D Converter Characteristics

$V_{\rm CC}$ = 5 V + 10%, $-$ 15%; $V_{\rm SS}$ = 0 V	$T_{\rm A}$ = 0 to 70 °C	for the SAB-C504
$4V \le V_{AREF} \le V_{CC} + 0.1 V$;	$T_{\rm A}$ = $-$ 40 to 85 $^{\circ}$ C	for the SAF-C504
$V_{\rm SS} - 0.1 \text{ V} \le V_{\rm AGND} \le V_{\rm SS} + 0.2 \text{ V};$	$T_{\rm A}$ = $-$ 40 to 110 °C	for the SAH-C504
	$T_{\rm A}$ = $-$ 40 to 125 $^{\circ}$ C	for the SAK-C504

Parameter	Symbol	Limit Values		Unit	Test Condition	
		min.	max.			
Analog input voltage	V_{AIN}	V_{AGND}	V_{AREF}	V	1)	
Sample time	ts	_	64 x t _{IN} 32 x t _{IN} 16 x t _{IN} 8 x t _{IN}	ns	Prescaler ÷ 32 Prescaler ÷ 16 Prescaler ÷ 8 Prescaler ÷ 4 2)	
Conversion cycle time	t_{ADCC}	-	384 x t _{IN} 192 x t _{IN} 96 x t _{IN} 48 x t _{IN}	ns	Prescaler ÷ 32 Prescaler ÷ 16 Prescaler ÷ 8 Prescaler ÷ 4 ³⁾	
Total unadjusted error	$T_{\sf UE}$	_	± 2	LSB	$V_{SS} + 0.5V \le V_{IN} \le V_{CC} - 0.5V^{4}$	
		_	± 4	LSB	$V_{SS} < V_{IN} < V_{SS} + 0.5V$ $V_{CC} - 0.5V < V_{IN} < V_{CC}$ ⁴⁾	
Internal resistance of reference voltage source	R_{AREF}	_	t _{ADC} / 250 - 0.25	kΩ	t _{ADC} in [ns] ^{5) 6)}	
Internal resistance of analog source	R_{ASRC}	_	<i>t</i> _S / 500 – 0.25	kΩ	t _s in [ns] ^{2) 6)}	
ADC input capacitance	C_{AIN}	_	50	pF	6)	

Notes see next page.

Clock calculation table :

Clock Prescaler Ratio	ADCL1, 0		tADC	t _S	tADCC
÷ 32	1	1	32 x t _{IN}	64 x t _{IN}	384 x t _{IN}
÷ 16	1	0	16 x t _{IN}	32 x t _{IN}	192 x t _{IN}
÷ 8	0	1	8 x t _{IN}	16 x t _{IN}	96 x t _{IN}
÷ 4	0	0	4 x t _{IN}	8 x t _{IN}	48 x t _{IN}

Further timing conditions : t_{ADC} min = 500 ns t_{IN} = 2 / f_{OSC} = 2 t_{CLCL}

Notes:

- V_{AIN} may exceed V_{AGND} or V_{AREF} up to the absolute maximum ratings. However, the conversion result in these cases will be X000_H or X3FF_H, respectively.
- 2) During the sample time the input capacitance C_{AIN} can be charged/discharged by the external source. The internal resistance of the analog source must allow the capacitance to reach their final voltage level within tg. After the end of the sample time tg, changes of the analog input voltage have no effect on the conversion result.
- 3) This parameter includes the sample time t_S, the time for determining the digital result and the time for the calibration. Values for the conversion clock t_{ADC} depend on programming and can be taken from the table on the previous page.
- 4) T_{UE} is tested at V_{AREF} = 5.0 V, V_{AGND} = 0 V, V_{CC} = 4.9 V. It is guaranteed by design characterization for all other voltages within the defined voltage range. If an overload condition occurs on maximum 2 not selected analog input pins and the absolute sum of input overload currents on all analog input pins does not exceed 10 mA, an additional conversion error of 1/2 LSB is permissible.
- 5) During the conversion the ADC's capacitance must be repeatedly charged or discharged. The internal resistance of the reference source must allow the capacitance to reach their final voltage level within the indicated time. The maximum internal resistance results from the programmed conversion timing.
- 6) Not 100 % tested, but guaranteed by design characterization.



AC Characteristics for C504-L / C504-2R

 $V_{\rm CC} = 5 \ {\rm V} + 10\%, -15\%; \ V_{\rm SS} = 0 \ {\rm V} \\ T_{\rm A} = -40 \ {\rm to} \ 85 \ ^{\circ}{\rm C} \\ T_{\rm A} = -40 \ {\rm to} \ 110 \ ^{\circ}{\rm C} \\ T_{\rm A} = -40 \ {\rm to} \ 110 \ ^{\circ}{\rm C} \\ T_{\rm A} = -40 \ {\rm to} \ 125 \ ^{\circ}{\rm C} \\ {\rm T_{\rm C}} = -40 \ {\rm to} \$

(C_1 for port 0, ALE and PSEN outputs = 100 pF; C_1 for all other outputs = 80 pF)

Program Memory Characteristics

Parameter	Symbol	Limit Values				
		12-MHz clock		Variable Clock 1/t _{CLCL} = 3.5 MHz to 12 MHz		
		min.	max.	min.	max.	
ALE pulse width	t _{LHLL}	127	_	2t _{CLCL} - 40	_	ns
Address setup to ALE	t _{AVLL}	43	_	t _{CLCL} - 40	_	ns
Address hold after ALE	t _{LLAX}	30	_	t _{CLCL} - 23	_	ns
ALE low to valid instr in	t _{LLIV}	-	233	_	$4t_{CLCL} - 100$	ns
ALE to PSEN	t_{LLPL}	58	-	t _{CLCL} - 25	_	ns
PSEN pulse width	t_{PLPH}	215	-	$3t_{\text{CLCL}} - 35$	_	ns
PSEN to valid instr in	t_{PLIV}	-	150	_	$3t_{CLCL} - 100$	ns
Input instruction hold after PSEN	t_{PXIX}	0	-	0	_	ns
Input instruction float after PSEN	t _{PXIZ} *)	-	63	_	$t_{\text{CLCL}} - 20$	ns
Address valid after PSEN	t _{PXAV} *)	75	-	<i>t</i> _{CLCL} – 8	_	ns
Address to valid instr in	t _{AVIV}	-	302	-	5t _{CLCL} - 115	ns
Address float to PSEN	t_{AZPL}	0	_	0	_	ns

[&]quot;) Interfacing the C504 to devices with float times up to 75 ns is permissible. This limited bus contention will not cause any damage to port 0 drivers.



AC Characteristics for C504-L / C504-2R (cont'd)

External Data Memory Characteristics

Parameter	Symbol		L	imit Values	Unit	
		12-MHz clock		Variable Clock 1/t _{CLCL} = 3.5 MHz to 12 MHz		
		min.	max.	min.	max.	
RD pulse width	t _{RLRH}	400	-	6t _{CLCL} - 100	_	ns
WR pulse width	t_{WLWH}	400	_	6t _{CLCL} - 100	_	ns
Address hold after ALE	t _{LLAX2}	114	-	2t _{CLCL} - 53	-	ns
RD to valid data in	t_{RLDV}	_	252		5t _{CLCL} - 165	ns
Data hold after RD	t_{RHDX}	0	-	0	-	ns
Data float after RD	t_{RHDZ}	_	97		2t _{CLCL} - 70	ns
ALE to valid data in	t_{LLDV}	_	517	-	8t _{CLCL} - 150	ns
Address to valid data in	t_{AVDV}	_	585	_	9t _{CLCL} - 165	ns
ALE to WR or RD	t _{LLWL}	200	300	$3t_{\text{CLCL}} - 50$	$3t_{\text{CLCL}} + 50$	ns
Address valid to WR or RD	t _{AVWL}	203	-	4t _{CLCL} - 130	-	ns
WR or RD high to ALE high	t _{WHLH}	43	123	t _{CLCL} - 40	t _{CLCL} + 40	ns
Data valid to WR transition	t _{QVWX}	33	-	t _{CLCL} - 50	-	ns
Data setup before WR	t _{QVWH}	433	-	7t _{CLCL} - 150	_	ns
Data hold after WR	t_{WHQX}	33	-	t _{CLCL} - 50	_	ns
Address float after RD	t _{RLAZ}	_	0	_	0	ns

External Clock Drive

Parameter	Symbol		Unit	
		Freq.		
		min.	max.	
Oscillator period	t_{CLCL}	83.3	294	ns
High time	t_{CHCX}	20	$t_{CLCL} - t_{CLCX}$	ns
Low time	t_{CLCX}	20	$t_{\text{CLCL}} - t_{\text{CHCX}}$	ns
Rise time	t_{CLCH}	_	20	ns
Fall time	t_{CHCL}	_	20	ns



AC Characteristics for C504-L24 / C504-2R24

 V_{CC} = 5 V + 10 %, - 15 %; V_{SS} = 0 V

 $T_A = 0$ to 70 °C

for the SAB-C504

 $T_{\rm A}$ = -40 to 85 °C

for the SAF-C504

(C_L for port 0, ALE and PSEN outputs = 100 pF; C_L for all other outputs = 80 pF)

Program Memory Characteristics

Parameter	Symbol	Limit Values				
		24-MHz clock		Variable Clock 1/t _{CLCL} = 3.5 MHz to 24 MHz		
		min.	max.	min.	max.	
ALE pulse width	t_{LHLL}	43	_	2t _{CLCL} - 40	_	ns
Address setup to ALE	t _{AVLL}	17	_	t _{CLCL} - 25	_	ns
Address hold after ALE	t_{LLAX}	17	_	t _{CLCL} - 25	_	ns
ALE low to valid instr in	t_{LLIV}	-	80		4t _{CLCL} - 87	ns
ALE to PSEN	t_{LLPL}	22	_	t _{CLCL} - 20	_	ns
PSEN pulse width	t_{PLPH}	95	_	$3t_{\text{CLCL}} - 30$	_	ns
PSEN to valid instr in	t_{PLIV}	-	60		$3t_{\text{CLCL}} - 65$	ns
Input instruction hold after PSEN	t_{PXIX}	0	_	0	_	ns
Input instruction float after PSEN	t _{PXIZ} *)	-	32	-	t _{CLCL} - 10	ns
Address valid after PSEN	t _{PXAV} *)	37	-	<i>t</i> _{CLCL} – 5	_	ns
Address to valid instr in	t _{AVIV}	-	148	_	5t _{CLCL} - 60	ns
Address float to PSEN	t_{AZPL}	0	-	0	_	ns

^{*)} Interfacing the C504 to devices with float times up to 37 ns is permissible. This limited bus contention will not cause any damage to port 0 drivers.



AC Characteristics for C504-L24 / C504-2R24 (cont'd) External Data Memory Characteristics

Parameter	Symbol		L	imit Values	Unit	
		24-MHz clock		Variable Clock 1/t _{CLCL} = 3.5 MHz to 24 MHz		
		min.	max.	min.	max.	
RD pulse width	t_{RLRH}	180	_	6t _{CLCL} - 70	-	ns
WR pulse width	t _{WLWH}	180	_	$6t_{\text{CLCL}} - 70$	_	ns
Address hold after ALE	t _{LLAX2}	56	_	2t _{CLCL} - 27	_	ns
RD to valid data in	t_{RLDV}	_	118	-	5t _{CLCL} - 90	ns
Data hold after RD	t_{RHDX}	0		0	-	ns
Data float after RD	t_{RHDZ}	_	63	_	2t _{CLCL} - 20	ns
ALE to valid data in	t_{LLDV}	_	200	_	8t _{CLCL} - 133	ns
Address to valid data in	t_{AVDV}	_	220	_	9t _{CLCL} - 155	ns
ALE to WR or RD	t_{LLWL}	75	175	$3t_{\text{CLCL}} - 50$	$3t_{\text{CLCL}} + 50$	ns
Address valid to WR	t _{AVWL}	67	_	4t _{CLCL} - 97	_	ns
WR or RD high to ALE high	t _{WHLH}	17	67	t _{CLCL} - 25	t _{CLCL} + 25	ns
Data valid to WR transition	t _{QVWX}	5	_	t _{CLCL} - 37	_	ns
Data setup before WR	t _{QVWH}	170	_	7t _{CLCL} - 122	_	ns
Data hold after WR	t _{WHQX}	15	_	t _{CLCL} - 27	_	ns
Address float after RD	t _{RLAZ}	_	0	_	0	ns

External Clock Drive

Parameter	Symbol		Unit	
		Freq.		
		min.	max.	
Oscillator period	t_{CLCL}	41.7	294	ns
High time	t_{CHCX}	12	$t_{\rm CLCL} - t_{\rm CLCX}$	ns
Low time	t_{CLCX}	12	$t_{\rm CLCL} - t_{\rm CHCX}$	ns
Rise time	t_{CLCH}	_	12	ns
Fall time	t_{CHCL}	_	12	ns



AC Characteristics for C504-L40 / C504-2R40

 V_{CC} = 5 V + 10 %, - 15 %; V_{SS} = 0 V

 $T_{\rm A}$ = 0 to 70 °C

for the SAB-C504

 $T_{\rm A} = -40 \text{ to } 85 \,^{\circ}\text{C}$

for the SAF-C504

($C_{\rm L}$ for port 0, ALE and PSEN outputs = 100 pF; $C_{\rm L}$ for all other outputs = 80 pF)

Program Memory Characteristics

Parameter	Symbol	Limit Values				
		40-MHz clock		Variable Clock 1/t _{CLCL} = 3.5 MHz to 40 MHz		
		min.	max.	min.	max.	
ALE pulse width	t_{LHLL}	35	-	2t _{CLCL} - 15	_	ns
Address setup to ALE	t_{AVLL}	10	_	t _{CLCL} - 15	_	ns
Address hold after ALE	t_{LLAX}	10	_	t _{CLCL} - 15	_	ns
ALE low to valid instr in	t_{LLIV}	_	55	_	$4t_{\text{CLCL}} - 45$	ns
ALE to PSEN	t_{LLPL}	10	-	t _{CLCL} - 15	_	ns
PSEN pulse width	t_{PLPH}	60	_	$3t_{\text{CLCL}} - 15$	_	ns
PSEN to valid instr in	t_{PLIV}	_	25	_	$3t_{\text{CLCL}} - 50$	ns
Input instruction hold after PSEN	t_{PXIX}	0	_	0	_	ns
Input instruction float after PSEN	t _{PXIZ} *)	_	20	_	$t_{\text{CLCL}} - 5$	ns
Address valid after PSEN	t _{PXAV} *)	20	-	$t_{\text{CLCL}} - 5$	_	ns
Address to valid instr in	t _{AVIV}	-	65	_	5t _{CLCL} - 60	ns
Address float to PSEN	t_{AZPL}	- 5	-	-5	_	ns

^{*)} Interfacing the C504 to devices with float times up to 25 ns is permissible. This limited bus contention will not cause any damage to port 0 drivers.



AC Characteristics for C504-L40 / C504-2R40 (cont'd) External Data Memory Characteristics

Parameter	Symbol		L	imit Values	Unit	
		40-MF	Iz clock	Variable Clock 1/t _{CLCL} = 3.5 MHz to 40 MHz		
		min.	max.	min.	max.	
RD pulse width	t_{RLRH}	120	_	$6t_{\text{CLCL}} - 30$	_	ns
WR pulse width	t _{WLWH}	120	_	6t _{CLCL} - 30	_	ns
Address hold after ALE	t _{LLAX2}	35	_	2t _{CLCL} - 15	_	ns
RD to valid data in	t_{RLDV}	_	75	-	$5t_{\text{CLCL}} - 50$	ns
Data hold after RD	t_{RHDX}	0		0	_	ns
Data float after RD	t_{RHDZ}	-	38		2t _{CLCL} - 12	ns
ALE to valid data in	t_{LLDV}	_	150	_	$8t_{CLCL} - 50$	ns
Address to valid data in	t_{AVDV}	_	150		9t _{CLCL} - 75	ns
ALE to WR or RD	t_{LLWL}	60	90	3t _{CLCL} - 15	$3t_{\text{CLCL}} + 15$	ns
Address valid to WR	t _{AVWL}	70	_	$4t_{\text{CLCL}} - 30$	_	ns
WR or RD high to ALE high	t _{WHLH}	10	40	t _{CLCL} - 15	t _{CLCL} + 15	ns
Data valid to WR transition	t _{QVWX}	5	_	t _{CLCL} - 20	_	ns
Data setup before WR	t _{QVWH}	125	_	$7t_{\text{CLCL}} - 50$	_	ns
Data hold after WR	t_{WHQX}	5	-	t _{CLCL} - 20	_	ns
Address float after RD	t _{RLAZ}	_	0	-	0	ns

External Clock Drive

Parameter	Symbol		Unit	
		Freq.		
		min.	max.	
Oscillator period	t_{CLCL}	25	294	ns
High time	t_{CHCX}	10	$t_{CLCL} - t_{CLCX}$	ns
Low time	t_{CLCX}	10	$t_{ m CLCL} - t_{ m CHCX}$	ns
Rise time	t_{CLCH}	_	10	ns
Fall time	t_{CHCL}	_	10	ns

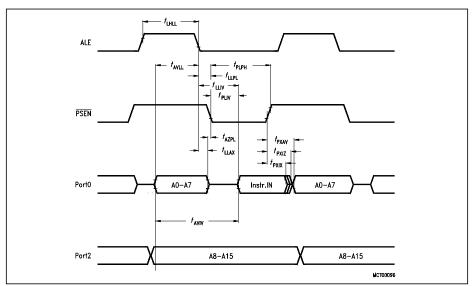


Figure 15 Program Memory Read Cycle

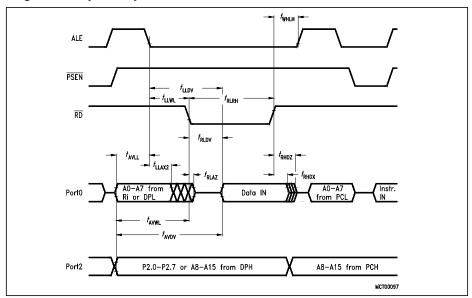


Figure 16 Data Memory Read Cycle

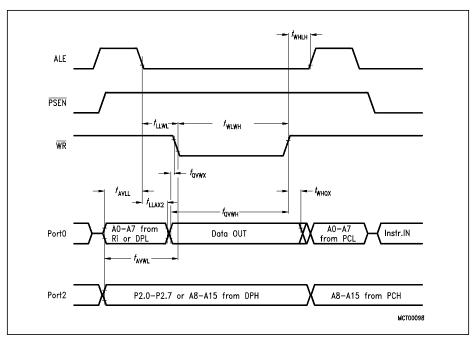


Figure 17
Data Memory Write Cycle

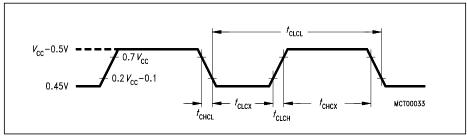


Figure 18
External Clock Cycle



ROM Verification Characteristics for C504-2R

ROM Verification Mode 1

Parameter	Symbol		Unit	
		min.	max.	
Address to valid data	t _{AVQV}	_	48 <i>t</i> _{CLCL}	ns
ENABLE to valid data	$t_{\sf ELQV}$	_	48 <i>t</i> _{CLCL}	ns
Data float after ENABLE	t_{EHQZ}	0	48 <i>t</i> _{CLCL}	ns
Oscillator frequency	1/t _{CLCL}	4	6	MHz

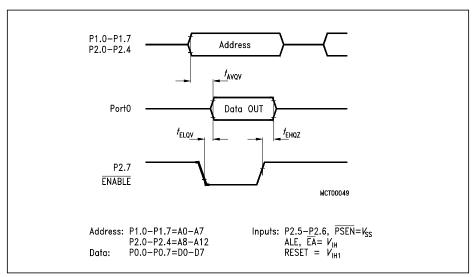


Figure 19 ROM Verification Mode 1

ROM Verification Mode 2

Parameter	Symbol		Unit		
		min.	typ	max.	
ALE pulse width	t _{AWD}	_	2 t _{CLCL}	_	ns
ALE period	t _{ACY}	_	12 t _{CLCL}	_	ns
Data valid after ALE	t _{DVA}	_	-	4 t _{CLCL}	ns
Data stable after ALE	t_{DSA}	8 t _{CLCL}	-	_	ns
P3.5 setup to ALE low	t _{AS}	_	t_{CLCL}	_	ns
Oscillator frequency	1/t _{CLCL}	4	_	6	MHz

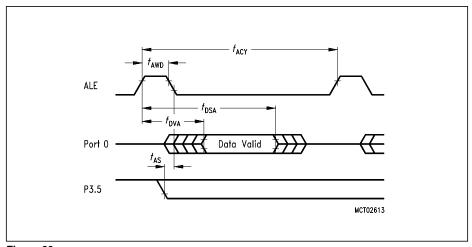
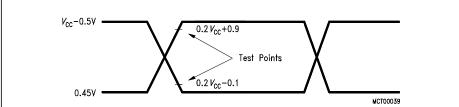
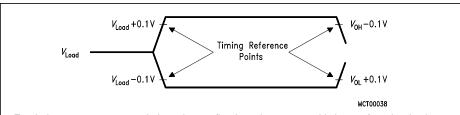


Figure 20 ROM Verification Mode 2



AC Inputs during testing are driven at $V_{\rm CC}$ – 0.5 V for a logic '1' and 0.45 V for a logic '0'. Timing measurements are made at $V_{\rm IHmin}$ for a logic '1' and $V_{\rm ILmax}$ for a logic '0'.

Figure 21
AC Testing: Input, Output Waveforms



For timing purposes a port pin is no longer floating when a 100 mV change from load voltage occurs and begins to float when a 100 mV change from the loaded $V_{\rm OH}/V_{\rm OL}$ level occurs. $I_{\rm OH}/I_{\rm OH} \ge \pm$ 20 mA

Figure 22 AC Testing : Float Waveforms

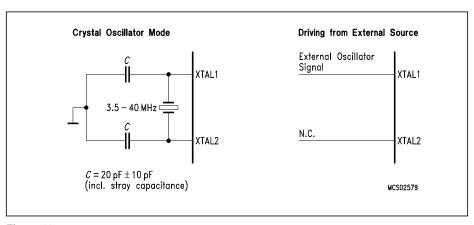


Figure 23
Recommended Oscillator Circuits for Crystal Oscillator

VAKAT